

P 14 x 8 Core and accessories

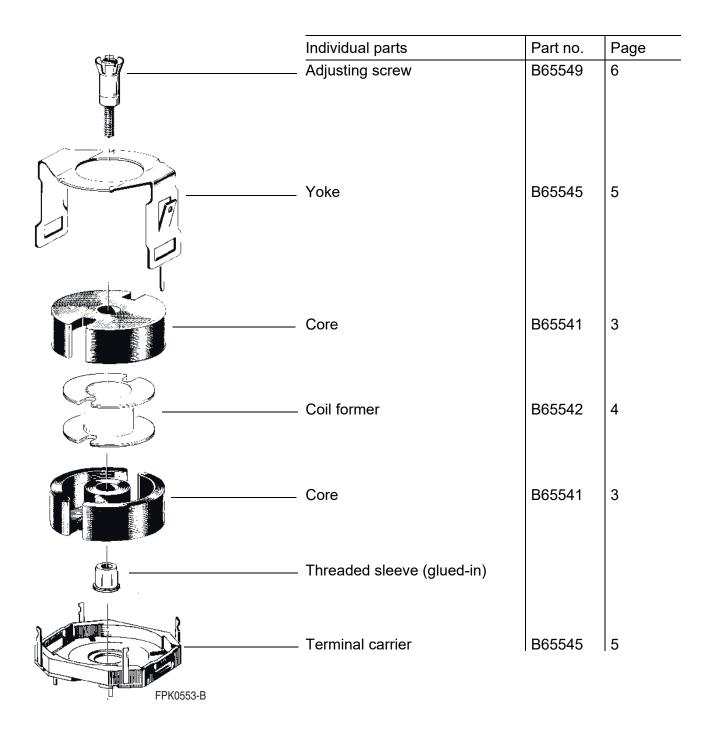
Series/Type: B65541, B65542, B65545, B65549

Date: October 2022

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Core and accessories



Example of an assembly set for printed circuit boards



Core B65541

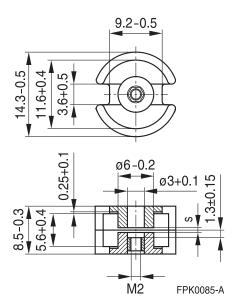
To IEC 63093-2Delivery mode: sets

Magnetic characteristics (per set)

	with center hole	without center hole	
ΣΙ/Α	0.8	0.73	mm ⁻¹
l _e	20	21	mm
I _e A _e A _{min}	25	28.7	mm ²
A_{min}	20	23.6	mm ²
V_e	500	603	mm ³

Approx. weight (per set)

m	3.2	3.5	g



Gapped (A_L values/air gaps examples)

Material	A _L value	s approx. mm	μ _e	Ordering code ¹⁾ -D with center hole -T with threaded sleeve
M33	100 ±3%	0.30	64	B65541+0100A033
N48	160 ±3% 250 ±3% 315 ±3% 400 ±3%	0.16 0.10 0.08 0.05	102 159 201 255	B65541+0160A048 B65541+0250A048 B65541+0315A048 B65541+0400A048

Ungapped

Material	A _L value	μ_{e}	P_V	Ordering code
				-D with center hole
	nH		W/set	-W without center hole
K1	140 +30/–20%	89		B65541D0000R001
M33	970 +30/–20%	618		B65541D0000R033
N48	2100 +30/–20%	1340		B65541D0000R048
N30	4600 +30/–20%	2680		B65541W0000R030
T38	9800 +40/–30%	5710		B65541W0000Y038
N87	2800 +30/–20%	1630	< 0.26 (200 mT, 100 kHz, 100 °C)	B65541W0000R087

Other A_L values/air gaps and materials available on request – see Processing remarks on page 7.

¹⁾ Replace the + by the code letter "D" or "T" for the required version.



Accessories B65542

Coil former

Standard: to IEC 63093-2

Material: GFR polyterephthalate (UL 94 V-0, insulation class to IEC 60085:

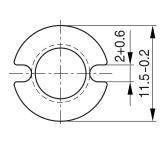
F ≙ max. operating temperature + 155 °C), color code black

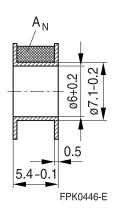
Crastin SK 645 FR [E41938 (M)], E I DUPONT DE NEMOURS & CO INC

Winding: see Processing notes, 2.1

Coil former			Ordering code	
Sections	A _N mm ²	I _N mm	A_R value $\mu\Omega$	
1	8.4	28	115	B65542B0000T001

Coil former







Accessories B65545

Mounting assembly for printed circuit boards

■ The set comprises a terminal carrier and a yoke

■ For snap-in connection

Terminal carrier

Material: GFR polyterephthalate (UL 94 V-0, insulation class to IEC 60085:

F

max. operating temperature 155 °C), color code gray

Pocan B4235® [E245249 (M)], LANXESS AG

Solderability: to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s

Resistance to soldering heat: to IEC 60068-2-20, test Tb, method 1B: 350 °C, 3.5 s

Yoke

Spring yoke, made of tinned bronze (0.3 mm), with ground terminal Packing mode: stick in EPS / PE foam board (Terminal carrier) / bulk package (Yoke)

Complete mounting assembly
(4 solder terminals)

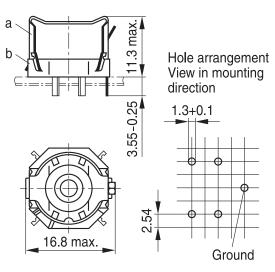
Complete mounting assembly
(6 solder terminals)

Ordering code: B65545B0009X000 Ordering code: B65545B0010X000

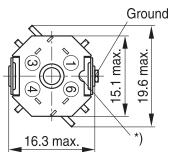
а

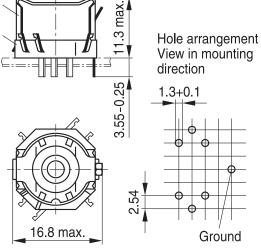
4 solder terminals

Ground 16.3 max. *)



6 solder terminals





FPK0447-M-E

^{*)} This recess must be on the side of the grounding pin to ensure that the yoke locks in position.

a) Yoke

b) Terminal carrier with 4 solder terminals

c) Terminal carrier with 6 solder terminals

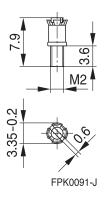


Accessories B65549

Adjusting screw

■ Tube core with thread and core brake made of GFR polyterephthalate Pocan B3235® [E245249 (M)], LANXESS AG

Tube core			Ordering code
$\emptyset \times \text{length (mm)}$	Material	Color code	
2.76 × 2.9	N22	black	B65549E0004X023





Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

Effects of core combination on A_L value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

Our ferrite accessories have been designed and evaluated only in combination with our ferrite cores. We explicitly point out that our ferrite accessories or our ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

We assume no warranty or reliability for the combination of our ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability
 problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter "Processing notes", section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.



Cautions and warnings

Display of ordering codes for TDK Electronics products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the company website or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.tdk-electronics.tdk.com/orderingcodes.



Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A_{e}	Effective magnetic cross section	mm ²
A_{L}	Inductance factor; $A_L = L/N^2$	nH
A_{L1}	Minimum inductance at defined high saturation ($\triangleq \mu_a$)	nH
A _{min}	Minimum core cross section	mm ²
A _N	Winding cross section	mm ²
A_R	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
В	RMS value of magnetic flux density	Vs/m ² , mT
ΔΒ	Flux density deviation	Vs/m², mT
Ê	Peak value of magnetic flux density	Vs/m ² , mT
ΔÂ	Peak value of flux density deviation	Vs/m ² , mT
B_{DC}	DC magnetic flux density	Vs/m ² , mT
B _R	Remanent flux density	Vs/m ² , mT
B _S	Saturation magnetization	Vs/m ² , mT
C_0	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
Ea	Activation energy	J
f	Frequency	s−1, Hz
f _{cutoff}	Cut-off frequency	s ⁻¹ , Hz
f _{max}	Upper frequency limit	s−1, Hz
f _{min}	Lower frequency limit	s ⁻¹ , Hz
f _r	Resonance frequency	s ^{−1} , Hz
f _{Cu}	Copper filling factor	
g	Air gap	mm
H	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H_{DC}	DC field strength	A/m
H _c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ⁻⁶ cm/A
h/μ_i^2	Relative hysteresis coefficient	10 ⁻⁶ cm/A
1	RMS value of current	Α
I _{DC}	Direct current	Α
Î	Peak value of current	A
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k ₃	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

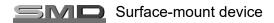
Symbol	Meaning	Unit
ΔL/L	Relative inductance change	Н
L_0	Inductance of coil without core	Н
L _H	Main inductance	Н
L_p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
L _s	Series inductance	Н
l _e	Effective magnetic path length	mm
I_N	Average length of turn	mm
N	Number of turns	
P_{Cu}	Copper (winding) losses	W
P _{trans}	Transferrable power	W
P_V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = $\omega L/R_s$ = 1/tan δ_l)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance (f = 0)	Ω
R _h	Hysteresis loss resistance of a core	Ω
ΔR_h	R _h change	Ω
R _i	Internal resistance	Ω
R_p	Parallel loss resistance of a core	Ω
R_s^r	Series loss resistance of a core	Ω
R_{th}	Thermal resistance	K/W
R_V	Effective loss resistance of a core	Ω
S	Total air gap	mm
Т	Temperature	°C
ΔT	Temperature difference	K
T_{C}	Curie temperature	°C
t	Time	s
t_v	Pulse duty factor	
tan δ	Loss factor	
tan δ_{l}	Loss factor of coil	
tan δ_r	(Residual) loss factor at $H \rightarrow 0$	
tan δ_{e}	Relative loss factor	
tan δ_h	Hysteresis loss factor	
tan δ/μ _i	Relative loss factor of material at H \rightarrow 0	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V_e	Effective magnetic volume	mm ³
Z	Complex impedance	Ω
Z_{n}	Normalized impedance $ Z _n = Z / N^2 \times \varepsilon (I_e / A_e)$	Ω/mm



Symbols and terms

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_{F}	Relative temperature coefficient of material	1/K
α _e	Temperature coefficient of effective permeability	1/K
r	Relative permittivity	
Þ	Magnetic flux	Vs
1	Efficiency of a transformer	
lB	Hysteresis material constant	mT-1
li	Hysteresis core constant	$A^{-1}H^{-1/2}$
'S	Magnetostriction at saturation magnetization	
,	Relative complex permeability	
0	Magnetic field constant	Vs/Am
а	Relative amplitude permeability	
арр	Relative apparent permeability	
е	Relative effective permeability	
i	Relative initial permeability	
p '	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)	
" p	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)	
r	Relative permeability	
rev	Relative reversible permeability	
s'	Relative real (inductive) component of $\overline{\mu}$ (for series components)	
s" S	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)	
tot	Relative total permeability	
	derived from the static magnetization curve	
	Resistivity	Ω m $^{-1}$
I/A	Magnetic form factor	mm ⁻¹
Cu	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	S
)	Angular frequency; ω = 2 Π f	s ⁻¹

All dimensions are given in mm.





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- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
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Release 2022-07